PCN13-2018 (New Wafer Sort Test Facility)

Dear Customer,

ams AG is pleased to inform you that a New Wafer Sort Test Facility has been opened in Asia. It is located in Tampines, Singapore and will enable us to support the ever increasing demand in today’s dynamic market environment.

Our business address is:

ams Sensors Asia Pte. Ltd. (Singapore Tampines)
JTC Nanopace
11 Tampines Industrial Crescent
Singapore 528606

This new test site is not only intended to increase the electrical testing capacity of ams AG but will also show a positive effect in the supply chain management of the products.
Other Advantages:

The new test facility is also strategically situated near to ams AG’s key assembly partners in Asia, both in wafer fabrication and manufacturing.

Key Partners Located in Asia

a) TSMC (Taiwan)
b) Amkor (Philippines and Korea)
c) ASE (Taiwan and Korea)
d) AIT (Indonesia)
e) Carsem (Malaysia)

Strategy:

1. Teams of test and quality experts were formed at ams AG (Austria) that will support, provide comprehensive trainings and be counterparts of the start-up team in Singapore.
2. The test equipment (e.g. probers) will all be identical to ams AG (Austria).
3. Specifications, product and process controls, trip limits, cut-off limits, acceptance criteria, including product packaging will be applied and implemented to all the products that will be tested in this new ams AG test site and will all be identical to ams AG (Austria).
4. Same specific device document (such as C-spec) will be used by ams Sensors Asia Pte. Ltd. (Singapore) except for the change in the test site information.

Impact on Product:

No impact on product is anticipated as there will be no changes in terms of form, fit and function.
## Process Flow Matrix:

<table>
<thead>
<tr>
<th>Process Flow</th>
<th>Old Test Site</th>
<th>New Test Site</th>
</tr>
</thead>
<tbody>
<tr>
<td>Wafer Fabrication</td>
<td>ams AG Austria</td>
<td>ams AG Austria</td>
</tr>
<tr>
<td>Sort</td>
<td>ams AG Austria</td>
<td>ams AG Austria or ams Sensors Asia Pte. Ltd. Singapore</td>
</tr>
<tr>
<td>Assembly</td>
<td>Amkor Philippines or Carsem (Malaysia)</td>
<td>Amko Philippines Carsem (Malaysia)</td>
</tr>
<tr>
<td>Rre Burnin Test</td>
<td>ams Austria</td>
<td>ams Austria</td>
</tr>
<tr>
<td>Burnin</td>
<td>SEMPAC or TSS (Test Solution Services Inc., separate PCN08-2018)</td>
<td>SEMPAC or TSS (Test Solution Services Inc., separate PCN08-2018)</td>
</tr>
<tr>
<td>Final Test</td>
<td>ams Austria</td>
<td>ams Austria</td>
</tr>
<tr>
<td>Tape &amp; Reel</td>
<td>ams Philippines</td>
<td>ams Philippines</td>
</tr>
<tr>
<td>Delivery</td>
<td>ams Philippines</td>
<td>ams Philippines</td>
</tr>
</tbody>
</table>
Product(s) affected:

<table>
<thead>
<tr>
<th>material ID</th>
<th>description</th>
</tr>
</thead>
<tbody>
<tr>
<td>186210071</td>
<td>AS5162-HSOP SOIC8 LF T&amp;RDP</td>
</tr>
<tr>
<td>186210086</td>
<td>AS5162-HSOM SOIC8 LF T&amp;RDP</td>
</tr>
</tbody>
</table>

Detailed activities and an actual status of this project are available upon request.

If you do have further questions, please do not hesitate to contact me.

Please be advised that unless we receive your written refusal concerning this PCN within 30 days, the PCN shall be deemed accepted.

Best regards,

Dietmar Gleispach
ams AG
Director Operations EAS